

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT3389037

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
WEI CHEN	06/08/2015
TONGZENG YANG	06/08/2015
KONGGANG WEI	06/08/2015
RECEIVING PARTY DATA	
Name:	FUTUREWEI TECHNOLOGIES, INC.
Street Address:	5340 LEGACY DRIVE
Internal Address:	SUITE 175
City:	PLANO
State/Country:	TEXAS
Postal Code:	75024
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14704240
CORRESPONDENCE DATA	
Fax Number:	(972)628-3616
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	972-628-3600
Email:	patents@munckwilson.com
Correspondent Name:	DOCKET CLERK/FWTI
Address Line 1:	P.O. DRAWER 800889
Address Line 4:	DALLAS, TEXAS 75380
ATTORNEY DOCKET NUMBER:	HUAW07-27762
NAME OF SUBMITTER:	ROBERT D. MCCUTCHEON
SIGNATURE:	/ROBERT D. MCCUTCHEON/
DATE SIGNED:	06/09/2015
Total Attachments: 2	
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source=Assignment#page2.tif	

ASSIGNMENT

WHEREAS, I/We, the undersigned inventor(s) (or one of the undersigned joint inventors), of residence as listed below, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made, the said application having been executed on the date set forth below; and

WHEREAS, Futurewei Technologies, Inc. ("Assignee"), a corporation organized and existing under the laws of Texas, with its principal office at 5340 Legacy Drive, Suite 175, Plano, TX 75024 is desirous of acquiring my/our entire right, title and interest in the said invention, and to the said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;




NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I/we assign and transfer to the Assignee and the Assignee's legal representatives, successors and assigns the full and exclusive right, title and interest in and to the invention in the United States and every foreign country and the entire right, title, and interest in and to the patent application and other such applications (e.g., provisional applications, non-provisional applications, continuations, continuations-in-part, divisional, reissues, reexaminations, National Phase applications, including petty patent applications, and utility model applications) that may be filed in the United States and every foreign country on the invention, and the patents, extensions, or derivations thereof, both foreign and domestic, that may issue thereon, and I/we do hereby authorize and request the Commissioner for Patents to issue U.S. patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to the Assignee agreeably with the terms of this assignment document.

I also hereby sell and assign to Assignee, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including, but not limited to, the right to file applications and obtain patents under the terms of the International Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to Assignee, or its successors, assigns, and legal representative, any facts know to me respecting said invention or the file history thereof, and at the expense of said assignee company, testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid such Futurewei, its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries.

ASSIGNMENT

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

Title of Invention	FAST SMP/ASMP MODE-SWITCHING HARDWARE APPARATUS FOR A LOW-COST LOW-POWER HIGH PERFORMANCE MULTIPLE PROCESSOR SYSTEM	
	Appl. No. 14/704,240	Filing Date: May 5, 2015
Signature of Inventor		
Inventor Name	<i>Wei Chen</i>	
Date	6/8/15	
Residence (City/State)	6624 Foxtail Way San Diego, California 92130	
Signature of Inventor		
Inventor Name	<i>Tongzeng Yang</i>	
Date	6/8/2015	
Residence (City/State)	13432 Moreton Glen San Diego, CA 92130	
Signature of Inventor		
Inventor Name	<i>Konggang Wei</i>	
Date	06/08/15	
Residence (City/State)	5590 Shannon Ridge Lane San Diego, CA 92130	